

Size 20161A

FEATURES

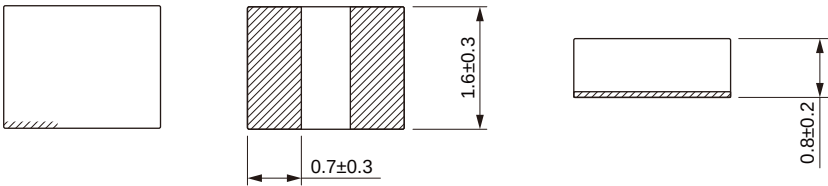
- High efficiency
- Low flux noise
- AEC-Q200 qualified
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APPLICATION

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Dimensions: [mm]

Land Pattern: [mm]



Electrical Properties:

| Part No | Inductance<br>@ 100KHz/1V<br>(μH) | Tolerance | Temperature<br>Rise Current<br>Typ.<br>(A) | Temperature<br>Rise Current<br>Max.<br>(A) | Satura on<br>Current<br>Typ.<br>(A) | Satura on<br>Current<br>Max.<br>(A) | DC<br>Resistance<br>Typ.<br>(mΩ) | DC<br>Resistance<br>Max.<br>(mΩ) |
|---------|-----------------------------------|-----------|--------------------------------------------|--------------------------------------------|-------------------------------------|-------------------------------------|----------------------------------|----------------------------------|
|         |                                   |           |                                            |                                            |                                     |                                     |                                  |                                  |
|         |                                   |           |                                            |                                            |                                     |                                     |                                  |                                  |
|         |                                   |           |                                            |                                            |                                     |                                     |                                  |                                  |
|         |                                   |           |                                            |                                            |                                     |                                     |                                  |                                  |
|         |                                   |           |                                            |                                            |                                     |                                     |                                  |                                  |
|         |                                   |           |                                            |                                            |                                     |                                     |                                  |                                  |





## Soldering Reflow:



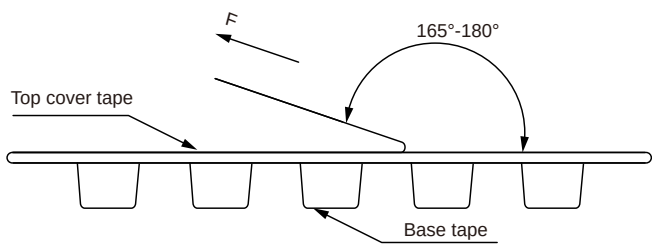
## Packaging Information:

### Tape Dimension:



| Series     | A0<br>(mm) | B0<br>(mm) | D<br>(mm) | P0<br>(mm) | P1<br>(mm) | W<br>(mm) | K0<br>(mm) | E<br>(mm)  | T<br>(mm)   |
|------------|------------|------------|-----------|------------|------------|-----------|------------|------------|-------------|
| MDTA20161A | 1.9 ± 0.1  | 2.3 ± 0.1  | 1.5 ± 0.1 | 4.0 ± 0.1  | 4 ± 0.1    | 8.0 ± 0.3 | 1.2 ± 0.1  | 1.75 ± 0.1 | 0.25 ± 0.05 |

### Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 0.98 N



Reel Dimension: [mm]

## Cautions and Warnings:

### Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate. The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

### Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
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